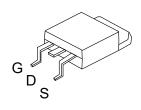


Feature

- High density cell design for lower Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high EAS
- Excellent package for good heat dissipation

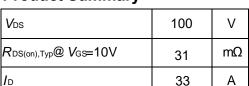
Application

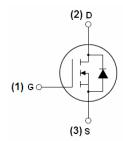
- Power switching application
- Hard switched and High frequency circuits
- Uninterruptible power supply



TO-263

Product Summary





| Parameter | Symbol | Limit | Unit |
|---|---------------------|------------|------|
| Drain-Source Voltage | V _{DS} | 100 | V |
| Gate-Source Voltage | V _G s | ±20 | V |
| Drain Current-Continuous | I _D | 33 | А |
| Drain Current-Pulsed (Note 1) | I _{DM} | 132 | А |
| Maximum Power Dissipation(Tc=25°C) | P _D | 70 | W |
| Single pulse avalanche energy ^(Note 2) | Eas | 96 | mJ |
| Operating Junction and Storage Temperature Range | T_{J} , T_{STG} | -55 To 175 | °C |

Thermal Characteristic

| Thermal Resistance,Junction-to-Case | Rелс | 1.15 | °C/W |
|---|------------------|------|------|
| Thermal Resistance, Junction-to-Ambient (PCB mount) | R _{θJA} | 40 | °C/W |



| Parameter | Symbol | Condition | | Тур | Max | Unit |
|--|---------------------|--|---|------|------|------|
| Off Characteristics | <u> </u> | | | • | • | • |
| Drain-Source Breakdown Voltage | BV _{DSS} | V _{GS} =0V I _D =250μA | | - | - | V |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} =100V,V _{GS} =0V | - | - | 1 | μΑ |
| Gate-Body Leakage Current | Igss | V _{GS} =±20V,V _{DS} =0V | - | - | ±100 | nA |
| On Characteristics | | | | | | • |
| Gate Threshold Voltage | V _{GS(th)} | V _{DS} =V _{GS} ,I _D =250µA | 1 | 1.7 | 2.5 | V |
| Davis Course On Chata Daviston - (Note 3) | 5 | V _{GS} =10V, I _D =12A | - | 31 | 37 | mΩ |
| Drain-Source On-State Resistance ^(Note 3) | R _{DS(ON)} | V _{GS} =4.5V, I _D = 8A | - | 32 | 42 | |
| Forward Transconductance | g FS | V _{DS} =5V,I _D =15A | | 11 | - | S |
| Dynamic Characteristics | | | | | | • |
| Input Capacitance | Clss | - V _{DS} =25V,V _{GS} =0V, - f=1.0MHz | | 2300 | - | pF |
| Output Capacitance | Coss | | | 215 | - | pF |
| Reverse Transfer Capacitance | Crss | | | 195 | - | pF |
| Switching Characteristics (Note 4) | | | | | | |
| Turn-on Delay Time | t _{d(on)} | | - | 29 | - | nS |
| Turn-on Rise Time | t _r | V _{DD} =50V, ID=20A, | | 13 | - | nS |
| Turn-Off Delay Time | t _{d(off)} | V _{GS} =10V,R _{GEN} =10Ω | - | 58.2 | - | nS |
| Turn-Off Fall Time | t _f | | - | 13.4 | - | nS |
| Total Gate Charge | Qg | V _{DS} =80V,I _D =20A V _{GS} =10V | | 55 | - | nC |
| Gate-Source Charge | Qgs | | | 15 | - | nC |
| Gate-Drain Charge | Q_{gd} | | | 20 | - | nC |
| Drain-Source Diode Characteristics | | | | | | • |
| Diode Forward Voltage | V_{SD} | V _{GS} =0V,I _S =20A | - | - | 1.2 | V |
| Reverse Recovery Time | T _{rr} | Tj=25℃,IF=10A,di/dt=100A/uS ^(note3) | | 58 | - | nS |
| Reverse Recovery Charge | Qrr | | | 110 | - | nC |

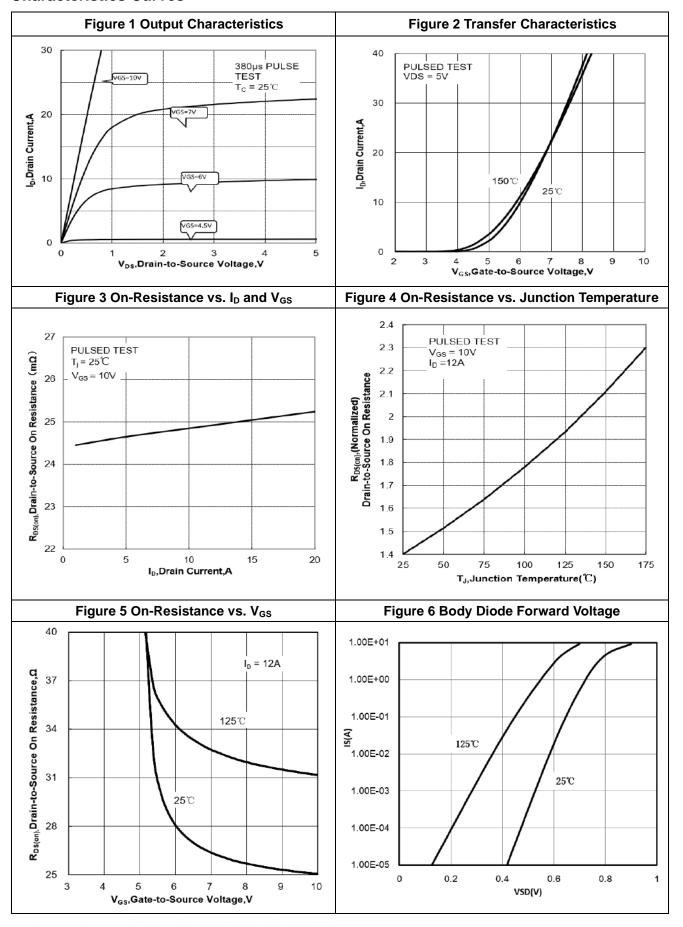
Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature. 2. E_{AS} condition :T $_{j}$ =25°C, V_{DD} =50V, V_{GS} =10V,L=0.5mH,Rg=25 Ω 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.

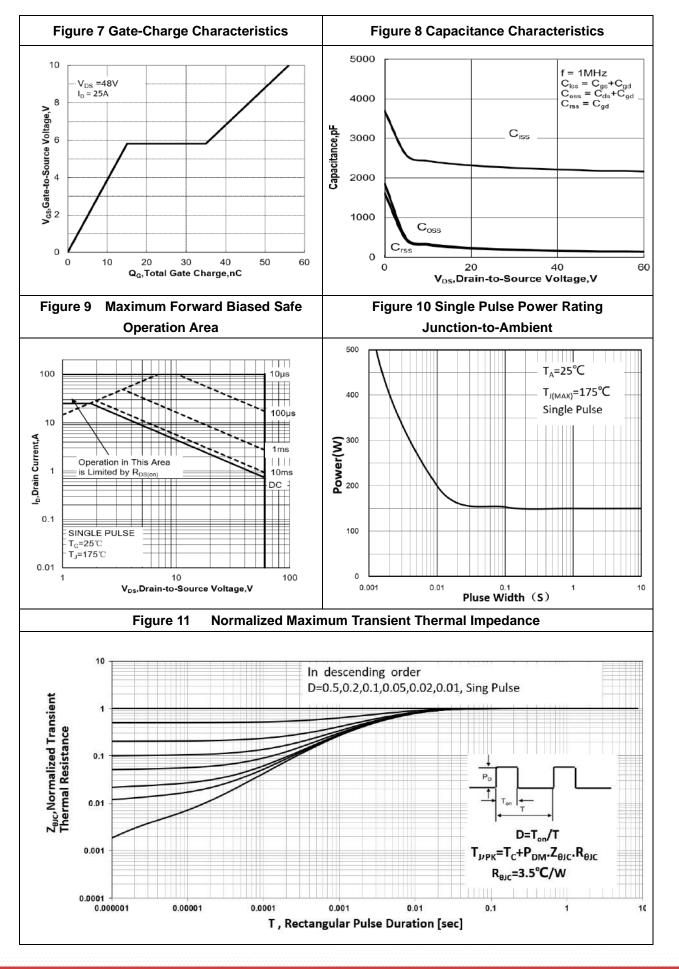
- 4. Guaranteed by design, not subject to production.



Characteristics Curves

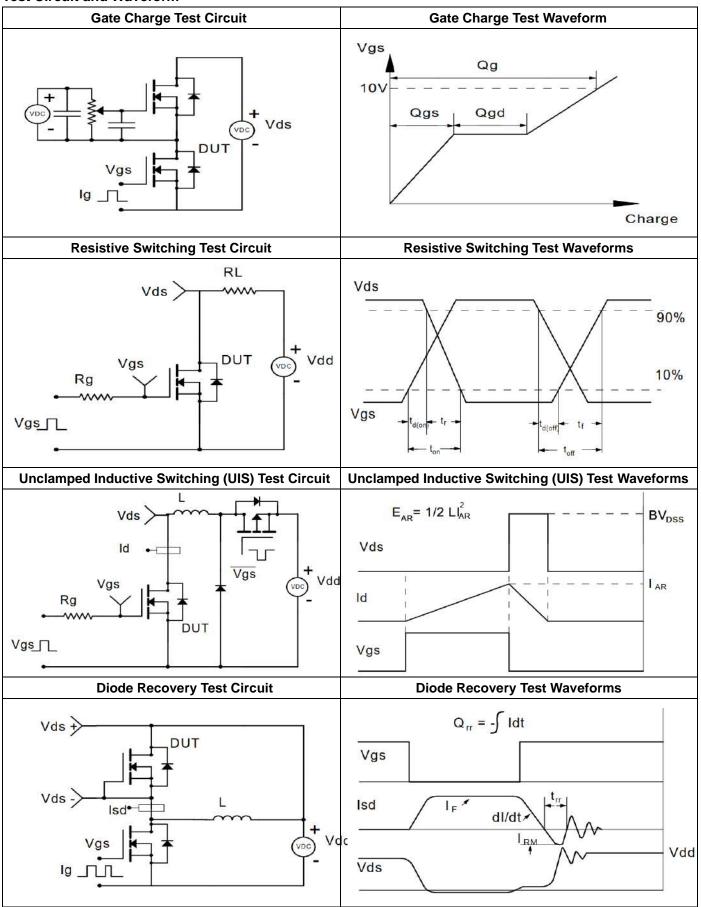








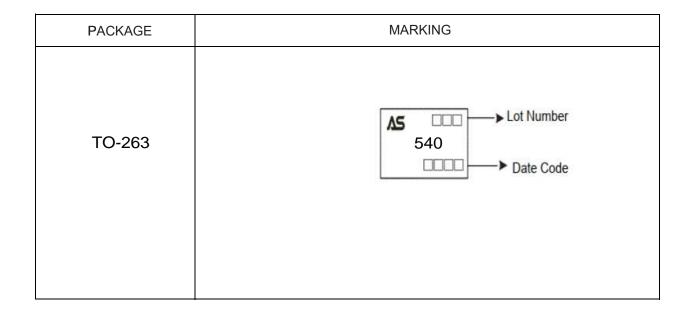
Test Circuit and Waveform



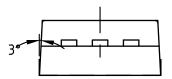


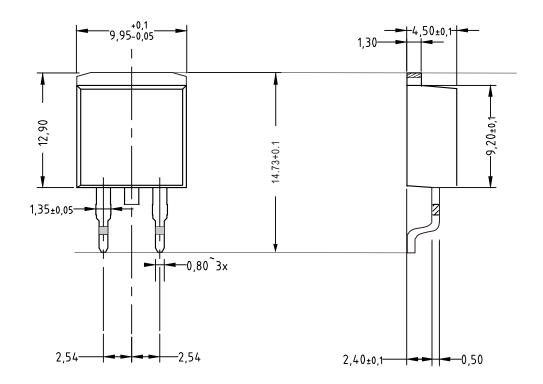
Ordering and Marking Information

| Ordering Device No. | Marking | Package | Packing | Quantity |
|---------------------|---------|---------|-----------|----------|
| ASDM540G-R | 540 | TO-263 | Tape&Reel | 800/Reel |



TO-263







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